Abstracts

A new via fence structure for crosstalk reduction in high density stripline packages

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Via fences are often placed between stripline conductors to suppress unwanted parallel plate mode coupling. However, if the striplines are too close to a fence, the coupling between the striplines is enhanced rather than reduced. In this paper we analyze the coupling between two striplines separated by a via fence using electromagnetic simulation for various dimensional parameters. Finally, we introduce a new via structure that significantly reduces the unwanted coupling.

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